

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	30307	(coordinate or position or x-y) same pad same (wir\$3 or bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 11:32
L2	1659	(coordinate or position or x-y) same pad same (wir\$3 or bond\$3)same tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 11:33
L3	109	2 and pad with height	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 11:34
L4	11	2 and pad with dummy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 11:34
S1	2	"20050067678".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 17:26
S2	1980	(438/14).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/05 13:47
S3	782	(438/15).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/05 13:47
S4	2493	S2 S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:47
S5	1	S4 and learn\$3 near touch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:14

S8	4	S4 and determin\$3 near3 pad near4 (position\$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:01
S9	0	S4 and dummy with pad near4 (position\$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:51
S10	174	S4 and pad near4 (position\$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:52
S11	1294	wire near2 bond\$3 with pad near4 (position\$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:52
S12	5	S11 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:54
S13	29	(wire with bonding with operation). clm. and "438"/\$.cls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:56
S14	250	wafer with bonding with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:57
S15	144	S14 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 13:57
S16	40	S15 and sensing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:01

S17	2597	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/05 14:46
S18	419	(438/617).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/05 14:01
S19	94	S18 and pad near4 (position\$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:06
S20	44	S18 and pad near4 (position\$3 coordinate)	USPAT	OR	ON	2005/11/05 14:01
S21	2902	S18 S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:06
S22	25	S21 and dummy with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:06
S23	17	S21 and dummy with pad	USPAT	OR	ON	2005/11/05 14:07
S24	51	S21 and (dummy with pad anchors)	USPAT	OR	ON	2005/11/05 14:07
S25	8	("5700735" "5734200" "5736791" "5773899" "5962919" "6002179").PN. OR ("6165886"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 14:12
S26	97	pad near4 height and S21	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 14:13
S27	66	pad near4 height and S21	USPAT	OR	ON	2005/11/05 14:13
S28	106	learn\$3 near touch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:14
S29	1	learn\$3 near touch\$3 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:15

S30	23	learn\$3 near touch\$3 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:16
S31	131	bonding with tool and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:17
S32	89	bonding with tool and S21	USPAT	OR	ON	2005/11/05 14:21
S33	74	S31 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:17
S34	68	S33 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:17
S35	44	S33 and wir\$3	USPAT	OR	ON	2005/11/05 14:17
S36	5	bonding with tool same dummy near3 pad	USPAT	OR	ON	2005/11/05 14:25
S37	2	bonding with tool same dummy near3 pad	US-PGPUB	OR	ON	2005/11/05 14:26
S38	5	bonding with tool same dummy near3 pad	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:29
S39	1	1989-321630.NRAN.	DERWENT	OR	ON	2005/11/05 14:28
S40	10	bonding and tool and dummy and pad	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:32
S41	17	height with pad with sensing	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:34
S42	10	height with pad with sensing	US-PGPUB	OR	ON	2005/11/05 14:35
S43	27	height with pad with sensing	USPAT	OR	ON	2005/11/05 14:35
S44	94	height with pad with tool	USPAT	OR	ON	2005/11/05 14:35
S45	36	height near5 pad with tool	USPAT	OR	ON	2005/11/05 14:38
S46	0	pad with coodinate	USPAT	OR	ON	2005/11/05 14:38
S47	1003	pad with coordinate	USPAT	OR	ON	2005/11/05 14:38
S48	36	pad near2 coordinate and wafer and tool	USPAT	OR	ON	2005/11/05 14:39
S49	557	reference near3 pad and tool	USPAT	OR	ON	2005/11/05 14:39

S50	42	reference near3 pad and tool and "438"/\$.ccls.	USPAT	OR	ON	2005/11/05 14:41
S51	5	bonding with tool same dummy with pad	USPAT	OR	ON	2005/11/05 14:41
S52	2	pad with coordinate and dummy adj pad	USPAT	OR	ON	2005/11/05 14:43
S53	33	pad with height same bonding with tool	USPAT	OR	ON	2005/11/05 14:44
S54	11400	pad near2 position	USPAT	OR	ON	2005/11/05 14:45
S55	131	S54 and bonding near3 tool	USPAT	OR	ON	2005/11/05 14:45
S56	23	S55 and pad with height	USPAT	OR	ON	2005/11/05 14:45
S57	257	S17 and pad with (coordinate positon location)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:49
S58	160	S57 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:47
S59	168	S57 and wir\$4 near2 bond\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:47
S60	65	S18 and pad with (coordinate positon location)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:53
S61	3042	(Wire with bonding with method).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:54
S62	3	S61 and (dummy with pad).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 14:54
S63	2	S61 and (dummy with pad).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:23

S64	7	S61 and (dummy with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:24
S65	0	determine with positon with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:24
S66	937	determine with position with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:24
S68	13	S66 and bonding with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:28
S69	10	S66 and wire with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:28
S70	77	("4342090" "4674670" "4765531" "5052606" "5082165" "5108023").PN. OR ("5307978"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:29
S71	1111	pad with (pressure stress) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:30
S72	5	S18 and pad with (pressure stress) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:31
S73	5	S18 and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:32
S74	9	S17 and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:32
S75	88	"438"/\$.ccls. and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:38
S76	80	(438/120).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/05 15:37

S77	3224	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/05 15:38
S78	209	S77 and pad with (pressure stress shock)	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/05 15:38
S79	218	S77 and pad with (pressure stress shock)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/05 15:38
S80	131	S79 and (wire wiring) with (bond bonding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 11:25